



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

P -CHANNEL ENHANCEMENT MODE POWER MOSFET**TF070P06N****• General Description**

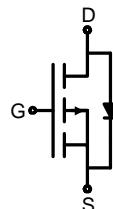
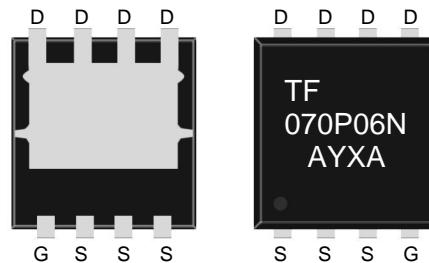
The TF070P06N combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

• Product Summary $V_{DS} = -60V$ $I_D = -100A$ $R_{DS(ON)(-10V\ typ)} = 6.9m\Omega$ $R_{DS(ON)(-4.5V\ typ)} = 8.3m\Omega$ **PDFNWB5x6-8L****• Ordering Information:**

Part NO.	TF070P06N
Marking 1	070P06N:TF070P06N
Marking 2	TF:tuofeng; Y:year code; X:Week; AA:device code;
MOQ	PDFN5060-8L:5000/PCS

• Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ T_C = 25^\circ C$	-100	A
	$I_D @ T_C = 75^\circ C$	-70	A
	$I_D @ T_C = 100^\circ C$	-60	A
Pulsed Drain Current ^①	I_{DM}	-345	A
Total Power Dissipation	$P_D @ T_C = 25^\circ C$	135	W
Total Power Dissipation	$P_D @ T_A = 25^\circ C$	2.0	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;



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Single Pulse Avalanche Energy	E_{AS}	760	mJ
Avalanche Current	I_{AS} I_{AR}	-30	A

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	3.2	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	45	° C/W
Soldering temperature, wave soldering for 8s	T_{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	-60			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	-1.1	-1.6	-2.3	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = -60V, V_{GS} = 0V$			-1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = -10V, I_D = -20A$		6.9	9.0	$m\Omega$
		$V_{GS} = -4.5V, I_D = -20A$		8.3	11.0	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = -20V, I_D = -20A$		23		S
Source-drain voltage	V_{SD}	$I_S = -20A$			1.20	V

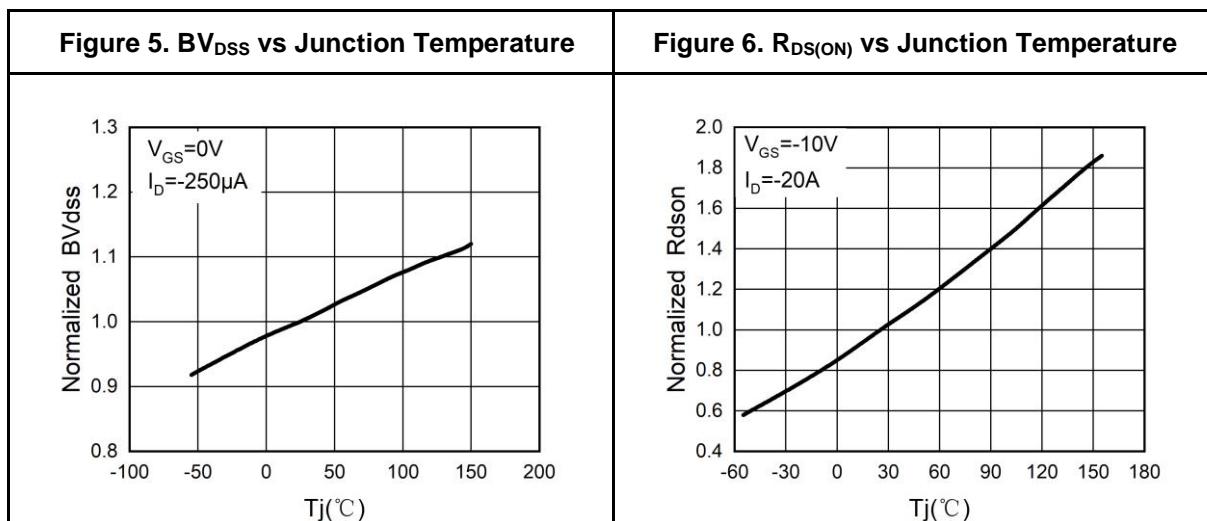
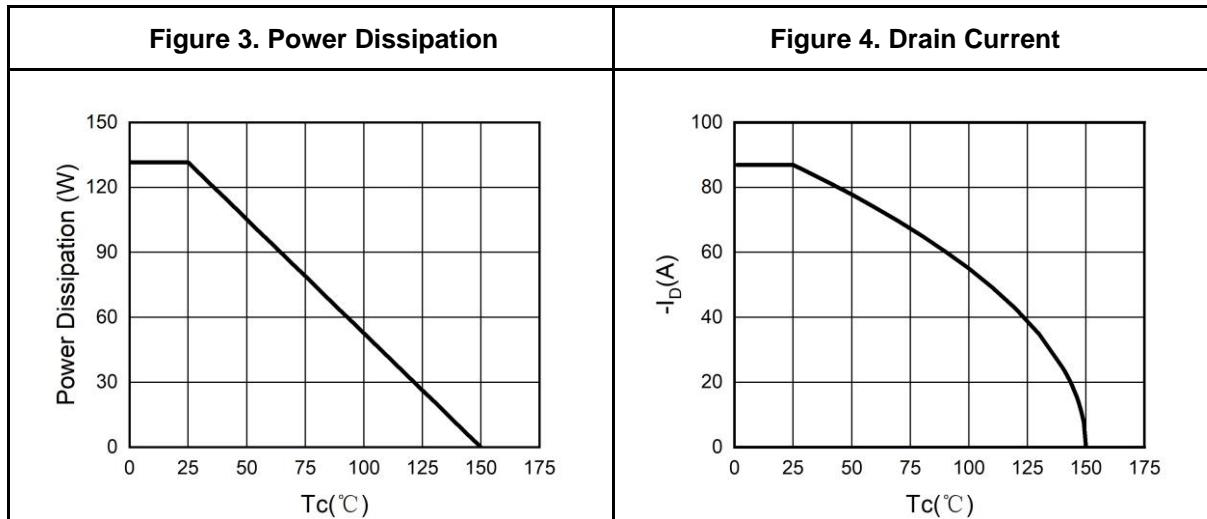
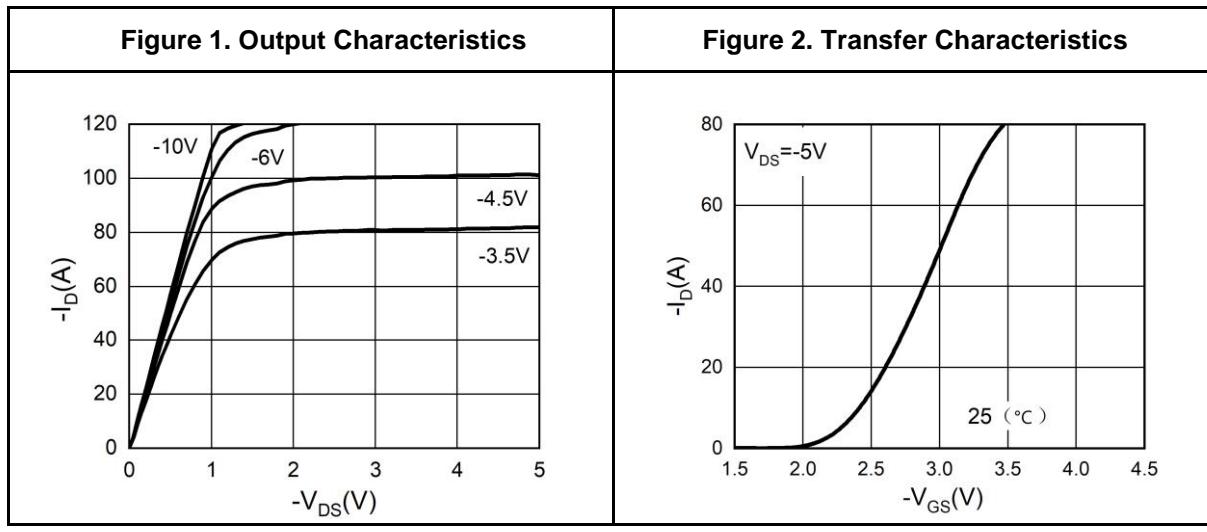
•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$V_{DS} = -30V, V_{GS} = 0V$ $f = 1MHz$	-	13336	-	pF
Output capacitance	C_{oss}		-	510	-	
Reverse transfer capacitance	C_{rss}		-	471	-	

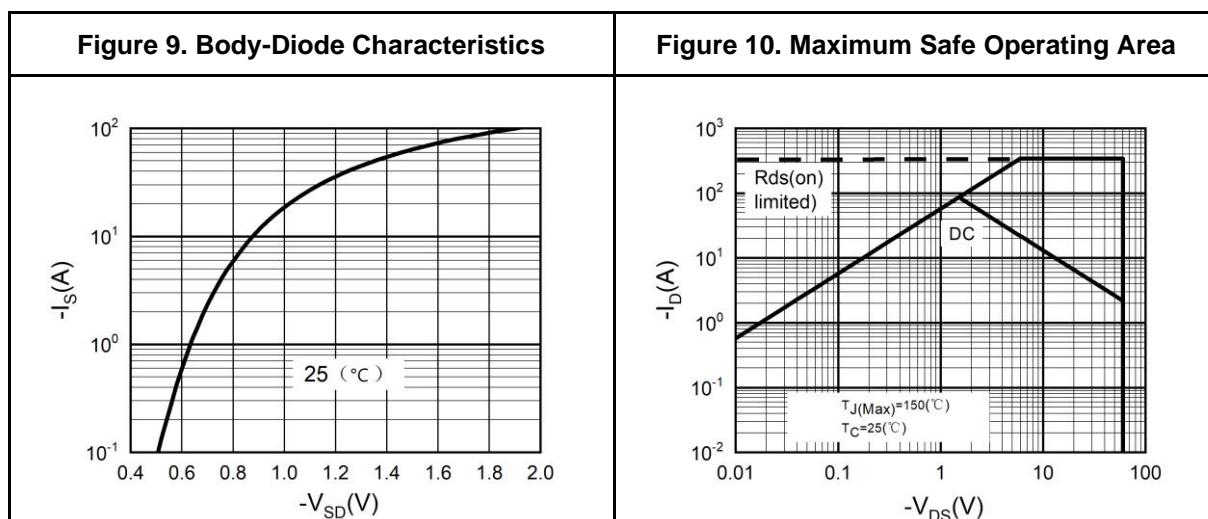
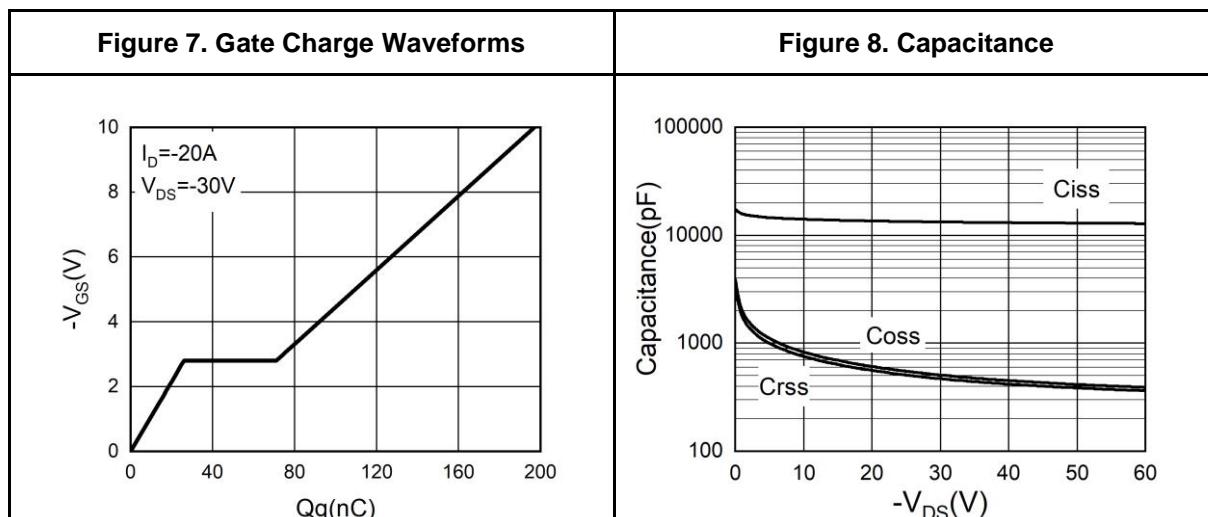
•Gate Charge characteristics($T_a = 25^\circ C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Gate Resistance	R_g	$f = 1MHz$		1.7		Ω
Total gate charge	Q_g	$V_{DD} = -30V$	-	197	-	nC
Gate - Source charge	Q_{gs}		-	26.0	-	
Gate - Drain charge	Q_{gd}		-	45.0	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS} = -10V, V_{DS} = -30V$		26		ns
Turn-ON Rise time	t_r			33		ns
Turn-Off Delay time	$t_{D(off)}$			274		ns
Turn-Off Fall time	t_f			90		ns

Typical Electrical And Thermal Characteristics (Curves)

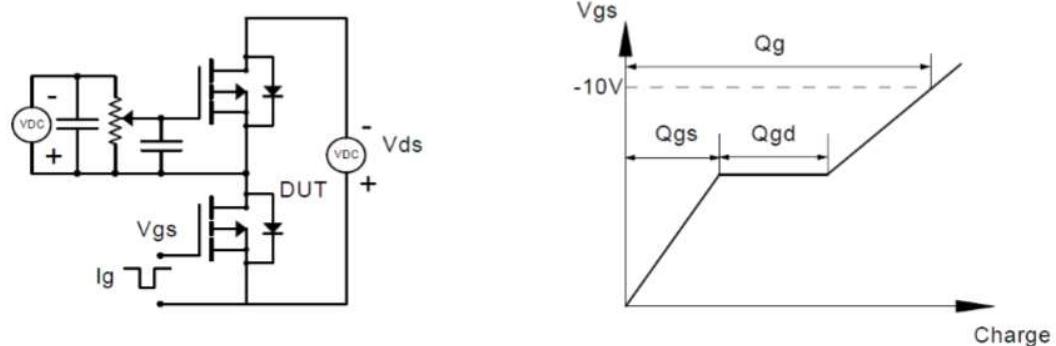


Typical Electrical And Thermal Characteristics (Curves)

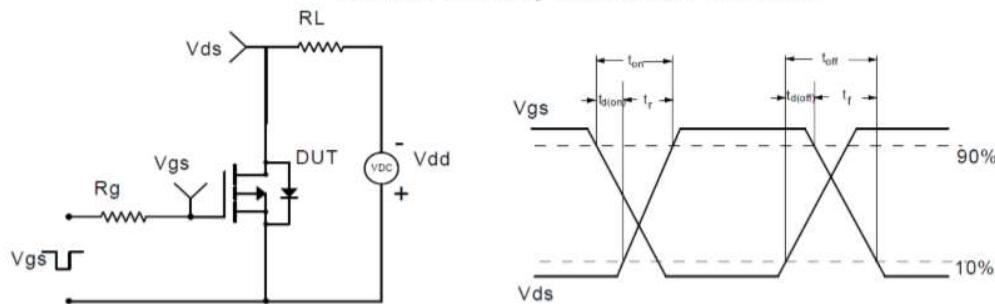


Test Circuit

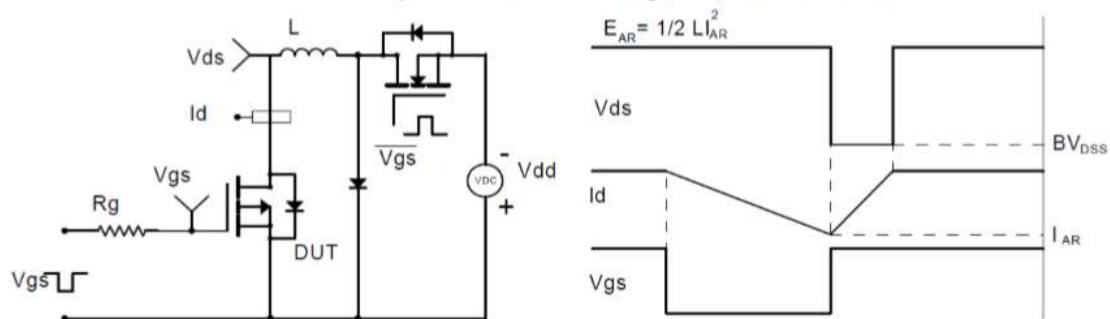
Gate Charge Test Circuit & Waveform



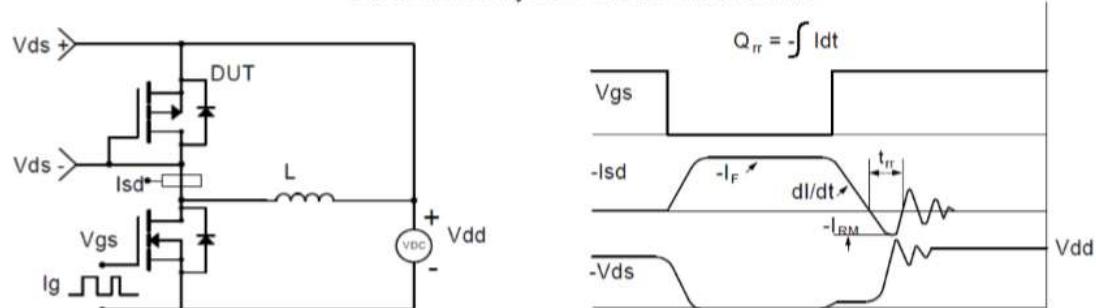
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



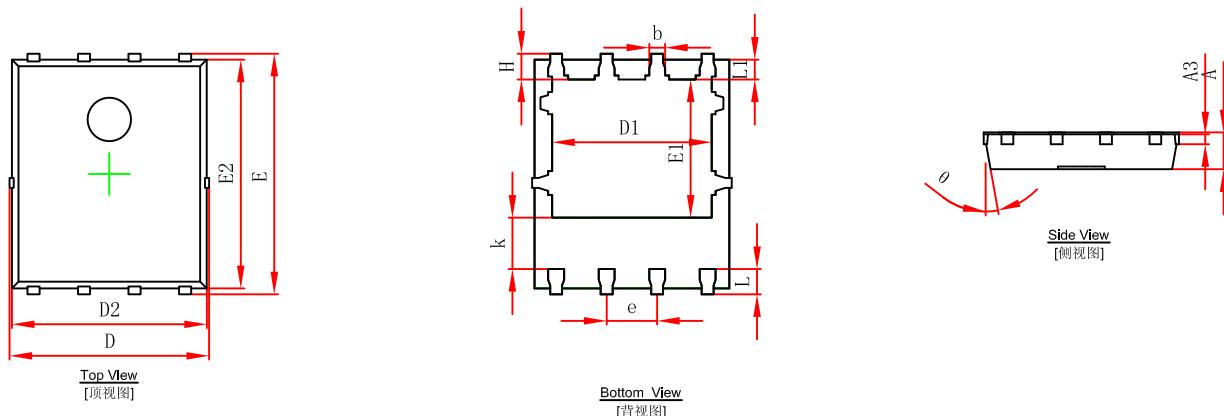


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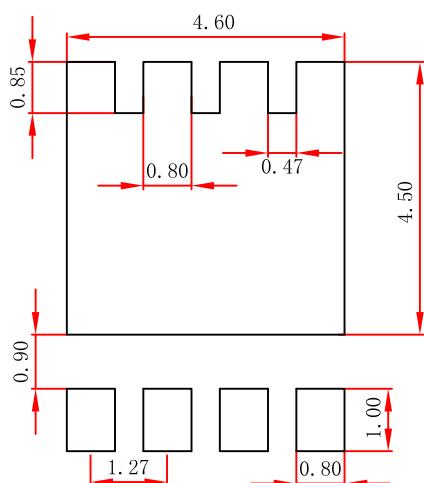
TF070P06N

PDFNWB5x6-8L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

PDFNWB5x6-8L Suggested Pad Layout



- Note:
1. Controlling dimension:in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.